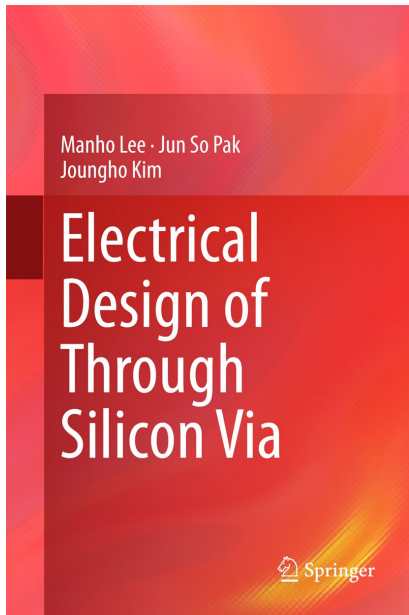




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Electrical Design of Through Silicon Via

- ▶ Provides fundamental modeling of TSV which is a very essential part of 3D ICs
- ▶ Includes both numerical formula analysis and qualitative explanations
- ▶ Approach from various view points: signal integrity, power integrity and etc.
- ▶ Has appeal for academia and industry

Through Silicon Via (TSV) is a key technology for realizing three-dimensional integrated circuits (3D ICs) for future high-performance and low-power systems with small form factors. This book covers both qualitative and quantitative approaches to give insights of modeling TSV in a various viewpoints such as signal integrity, power integrity, and thermal integrity. Most of the analysis in this book include simulations, numerical modelings and measurements for verification. The author and co-authors in each chapter have studied deep into TSV for many years and the accumulated technical know-hows and tips for related subjects are comprehensively covered.

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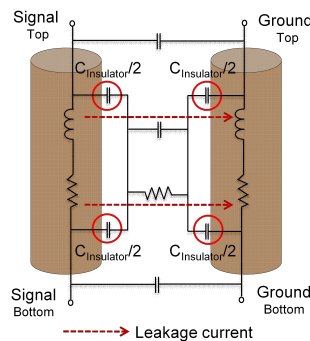
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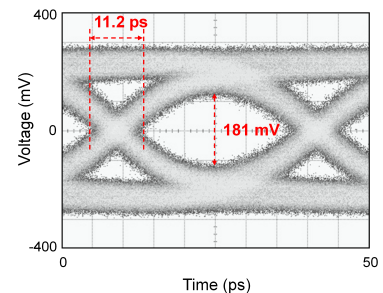
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